

Title (en)
Method of molding and tentative retention

Title (de)
Verfahren zur Formung und vorläufigen Befestigung

Title (fr)
Procédé de moulage et de retenue provisoire

Publication
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Application
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Abstract (en)
A molding and tentatively retaining mold 10 of the invention has a plurality of molds which are relatively movable with respect to a fixed mold, and molds a housing 31 and rear holders 32 and 33, which are respectively independent, in a plurality of cavities formed in cooperation with the fixed mold. When the rear holders 32 and 33 are relatively moved with respect to the housing 31 by a pair of rear-holder tentatively retaining cylinders 19 after molding, and are tentatively retained, the amount of movement of a pair of third movable molds 14 is set to be greater by a predetermined amount than an amount of movement necessary for tentatively retaining the rear holders 32 and 33, and the third movable molds 14 after movement are stopped at the moved positions until a predetermined time elapses. <IMAGE>

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